#### TOSHIBA Rectifier Silicon Diffused Type

# **CMG02**

#### General-Purpose Rectifier Applications

- Repetitive peak reverse voltage :  $V_{RRM} = 400 V$ •
- Average forward current : IF (AV) = 2.0 A •
- Suitable for high-density board assembly due to the use of a small Toshiba Nickname: M-FLAT<sup>TM</sup>

#### Absolute Maximum Ratings (Ta = 25°C)

| Characteristics                           | Symbol           | Rating     | Unit |
|---|------------------|------------|------|
| Repetitive peak reverse voltage           | VRRM             | 400        | V    |
| Average forward current                   | lf (AV)          | 2.0        | (A ) |
| Non-repetitive peak forward surge current | IFSM             | 80 (50 Hz) | A    |
| Junction temperature                      | Tj               | -40 to 150 | С    |
| Storage temperature                       | T <sub>stg</sub> | -40 to 150 | °C   |

0.65±0. 3.8±0.1 0.65 ±0.2 .75 ±0.1 0.16 ±0.06 2.4 +0.2 1 ANODE 2 CATHODE JEDEC JEITA TOSHIBA 3-4E1S Weight: 0.023 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Plea lity Handbook ("Ha reliability test repo

### Electrical

| Characteristics                             | Symbol    | Test Condition  | Min | Тур. | Max | Unit |
|---|-----------|---|-----|------|-----|------|
|   | VFM(1)    | I <sub>FM</sub> =1.0 A (pulse test)   | _   | 0.86 | _   | V    |
| Peak forward voltage                        | VFM(2)    | IFM = 2.0 A (pulse test)  |     | 0.9  | 1.1 | V    |
| Repetitive peak reverse current             | IRRM      | V <sub>RRM</sub> = 400 V (pulse test)   | _   |      | 10  | μA   |
| Thermal resistance<br>(junction to ambient) |           | Device mounted on a ceramic board<br>board size 50 mm × 50 mm<br>soldering land size 2 mm × 2 mm<br>board thickness 0.64 mm   | _   | _    | 60  |      |
|   | Rth (j-a) | $\begin{array}{ccc} \text{Device mounted on a glass-epoxy board} \\ \text{board size} & 50 \text{ mm} \times 50 \text{ mm} \\ \text{soldering land size} & 6 \text{ mm} \times 6 \text{ mm} \\ \text{board thickness} & 1.6 \text{ mm} \end{array}$     | _   | _    | 110 | °C/W |
|   |           | $\begin{array}{ccc} \text{Device mounted on a glass-epoxy board} \\ \text{board size} & 50 \text{ mm} \times 50 \text{ mm} \\ \text{soldering land size} & 2.1 \text{ mm} \times 1.4 \text{ mm} \\ \text{board thickness} & 1.6 \text{ mm} \end{array}$ | _   | _    | 180 |      |
| Thermal resistance<br>(junction to lead)    | Rth (j-ł) | _   | _   | _    | 16  | °C/W |

Start of commercial production 2002-11

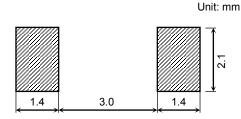
| • • • •              | iate reliability<br>erating Conc | upon reviewing the Toshiba Semicone<br>cept and Methods") and individual relia  |           |      |
|----------------------|----------------------------------|---|-----------|------|
| Characteristics      | (Ta = 25°C                       |   |           |      |
| Characteristics      | Symbol                           | Test Condition  | Min       | Тур. |
| rd voltage           | VFM(1)                           | IFM =1.0 A (pulse test)   | t) — 0.86 |      |
|                      | V <sub>FM(2)</sub>               | I <sub>FM</sub> = 2.0 A (pulse test)  |           | 0.9  |
| peak reverse current | IRRM                             | V <sub>RRM</sub> = 400 V (pulse test)   |           |      |
|                      |                                  | Device mounted on a ceramic board<br>board size 50 mm × 50 mm<br>soldering land size 2 mm × 2 mm<br>board thickness 0.64 mm | _         | _    |

Unit: mm

# <u>TOSHIBA</u>

#### Marking

|   | Abbreviation Code                          | Part No. | Cathode mark and Lot code |  |  |  |  |  |
|---|--|----------|---------------------------|--|--|--|--|--|
|   | G2   | CMG02    | G2 (or abbreviation code) |  |  |  |  |  |
|   |  |          |                           |  |  |  |  |  |
| L | Land pattern dimensions for reference only |          |                           |  |  |  |  |  |

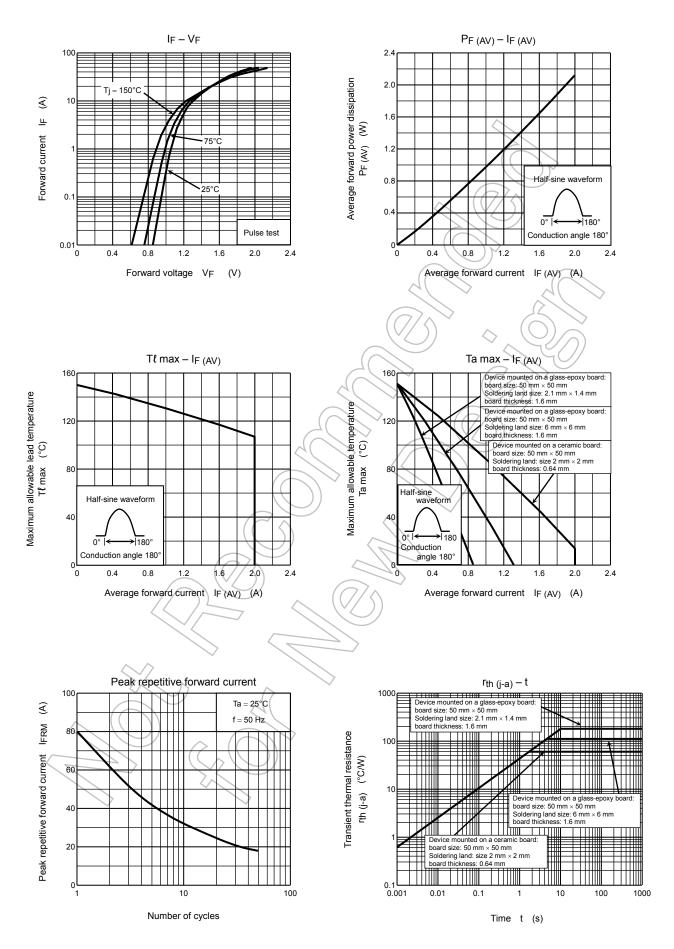


#### **Handling Precaution**

- 1) The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.
  - V<sub>RRM</sub>: We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of V<sub>RRM</sub> for a DC circuit and be no greater than 50% of that of V<sub>RRM</sub> for an AC circuit.
     V<sub>RRM</sub> has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.
  - IF (AV):We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF (AV) and T<sub>j</sub> be below 120°C. When using this device, take the margin into consideration by using an allowable Ta max-IF (AV) curve.
  - IFSM: This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180. Therefore, this is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.
  - Tj : We recommend that a device be used at Tj below 120°C under the worst load and heat radiation conditions.
- 2) Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.

3) For other design considerations, see the Toshiba website.

## **TOSHIBA**



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